

PLEASE CHECK WWW.MOLEX.COM FOR LATEST PART INFORMATION

Part Number: [0739432200](#)
Status: **Active**
Overview: [HDM Backplane Connector System](#)
Description: HDM Board-to-Board Backplane Header, Vertical, Solder Tail, Closed End, 72 Circuits

Documents:

3D Model	Packaging Specification PK-70873-0818 (PDF)
Drawing (PDF)	RoHS Certificate of Compliance (PDF)
3D Model (PDF)	

Agency Certification

CSA	LR19980
UL	E29179

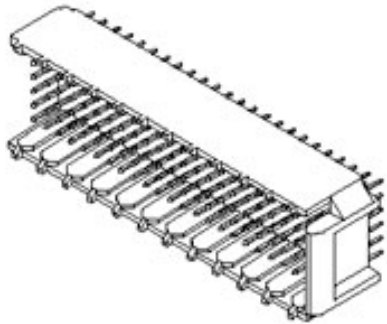
General

Product Family	Backplane Connectors
Series	73943
Application	Backplane
Comments	Solder Tail, Solder Tail
Component Type	PCB Header
Overview	HDM Backplane Connector System
Product Name	HDM
UPC	800754019972

Physical

Circuits (Loaded)	72
Circuits (maximum)	72
Color - Resin	Black, Natural
Durability (mating cycles max)	250
First Mate / Last Break	No
Flammability	94V-0
Guide to Mating Part	No
Keying to Mating Part	None
Material - Metal	Phosphor Bronze
Material - Plating Mating	Gold
Material - Plating Termination	Tin
Material - Resin	High Temperature Thermoplastic
Net Weight	3.554/g
Number of Columns	12
Number of Pairs	Open Pin Field
Number of Rows	6
Orientation	Vertical
PC Tail Length	2.50mm
PCB Locator	No
PCB Retention	None
PCB Thickness - Recommended	2.50mm
Packaging Type	Tube
Pitch - Mating Interface	2.00mm
Pitch - Termination Interface	2.00mm
Plating min - Mating	0.762µm
Plating min - Termination	2.540µm
Stackable	Yes
Surface Mount Compatible (SMC)	Yes
Temperature Range - Operating	-55° to +105°C
Termination Interface: Style	Through Hole

Electrical



Series image - Reference only

EU ELV

Not Relevant

EU RoHS

Compliant

China RoHS

REACH SVHC

Not Contained Per -
ED/71/2019 (16 July
2019)

Halogen-Free

Status

Low-Halogen

For more information, please visit [Contact US](#)

China ROHS	Green Image
ELV	Not Relevant
RoHS Phthalates	Not Contained

Search Parts in this Series

[73943](#) Series

Mates With

[73632](#) HDM+ Board-to-Board Daughtercard
Receptacle. [73780](#) HDM Board-to-Board
Daughtercard Receptacle

Application Tooling | FAQ

*Tooling specifications and manuals are
found by selecting the products below.
Crimp Height Specifications are then
contained in the Application Tooling
Specification document.*

Global

Description	Product #
Extraction Tool	621001000
Backplane Insertion	621001400
Signal Contact Tool	
Backplane Signal	622008502
Insertion Module	
Press-In Tool for 2.00mm Pitch HDM*	
Board-to-Board Backplane Header	

Current - Maximum per Contact	1.0A
Data Rate	1.0 Gbps
Voltage - Maximum	250V AC
Solder Process Data	
Duration at Max. Process Temperature (seconds)	040
Lead-freeProcess Capability	SMC&WAVE
Max. Cycles at Max. Process Temperature	003
Process Temperature max. C	260
Material Info	
Reference - Drawing Numbers	
Packaging Specification	PK-70873-0818
Sales Drawing	SD-73943-001

This document was generated on 12/17/2019

PLEASE CHECK WWW.MOLEX.COM FOR LATEST PART INFORMATION

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

[Molex:](#)

[73943-2200](#)